

# LAMP 2015

The 7th International Congress on Laser Advanced Materials Processing

**DATE:** May 26-29, 2015  
**VENUE:** Kitakyushu International Conference Center, Fukuoka, Japan  
**ORGANIZER:** Japan Laser Processing Society (JLPS)  
**WEBSITE:** <http://www.jlps.gr.jp/lamp/lamp2015>

## REGISTRATION & SUBMISSION

**Presentation type** Oral /Poster Presentation  
**Abstract submission** December 15, 2014  
**Early registration** March 1, 2015  
(All presenting authors are required to complete the registrations prior to Early Registration)  
**Proceedings** Submission due date : May 26, 2015 (DAY1)  
Proceeding of LAMP2015 will be published after the congress. Please submit your manuscript(s) through website. Manuscript Guidelines and Template will be available online.

## TRANSPORTATION



## AIM AND SCOPE

Welcome to LAMP2015!

The International Congress on Laser Advanced Materials Processing (LAMP) deals with science and technology of advanced laser materials processing covering precision microfabrication and high power laser processing. LAMP2015 is held during May 26 - 29, 2015 in Fukuoka, Japan. LAMP2015 consists of International Symposia on Laser Precision Microfabrication (LPM) and High Power Laser Processing (HPL) and covers hardware as well as software for fundamental research and industrial applications in both micro and macro processing. LAMP2015 is planned as a four-day event with a plenary session, oral and poster sessions, special sessions dealing with topical issues, and the exhibition with inviting most important world authorities in this field.

The aim of this congress is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of laser materials processing, and topics for the next generation with fundamental scientists, end users and laser manufactures. We expect that LAMP2015 would play an important role not only for understanding fundamental knowledge of laser materials processing but also forecasting future technologies to be developed and the future laser market.

Dr. Koji Sugioka, General Chair, LAMP2015

## LPM TOPICS

1. Fundamental aspects  
(Dynamics, modeling, simulation, etc.)
2. Process monitoring and control
3. Laser and photochemistry
4. Nanotechnology
5. Laser-based direct-write techniques
6. Ultra-short pulse laser processing
7. VUV laser and X-ray processing
8. Surface treatment  
(Texturing, cleaning, annealing, modification, etc.)
9. Advanced laser processing  
(Fiber laser, disc laser, FEL, etc.)
10. Micro-patterning and micro-structuring
11. Micro-machining
12. 3-D micro- and nano-fabrication
13. Drilling and cutting
14. Micro-welding and micro-bonding
15. Micro-forming
16. Wafer dicing
17. Marking and trimming
18. Glass/Ceramic processing
19. Packaging and mounting process
20. Lithography  
(including EUV source and application)
21. Manufacture of micro devices and systems
22. Film deposition and synthesis of  
advanced materials (PLD, CVD, etc)
23. Nano- and micro-particles
24. Medical and biological applications
25. Optics and systems for laser microprocessing
26. Laser devices
27. Industrial applications
28. Others
29. Special Session 1: TBA
30. Special Session 2: TBA
31. Special Session 3: TBA

## HPL TOPICS

1. Fundamentals of laser-materials interactions
2. Laser-induced plasma
3. Monitoring and control
4. Modeling and simulation
5. Materials and metallurgical aspects
6. Evaluation of properties  
(Strength, etc.)
7. High power laser diode
8. Solid-state laser  
(YAG, Fiber, Disk, etc.)
9. Gas laser
10. Optics
11. Beam delivery system
12. Welding
13. Welding of light metals and alloys
14. Joining of plastics
15. Joining of glasses or ceramics
16. Joining of dissimilar materials
17. Joining of battery or fuel cell
18. Remote welding
19. Hybrid welding
20. Brazing and soldering
21. Drilling and cutting
22. Cleaning
23. Surface modification  
(Quenching, alloying, etc.)
24. Cladding
25. Rapid prototyping
26. Additive manufacturing (3D Printer)
27. New and innovative applications  
(Sandwich panel, etc.)
28. Industrial applications
29. Present status and future prospects
30. Others

CONTACT US

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